

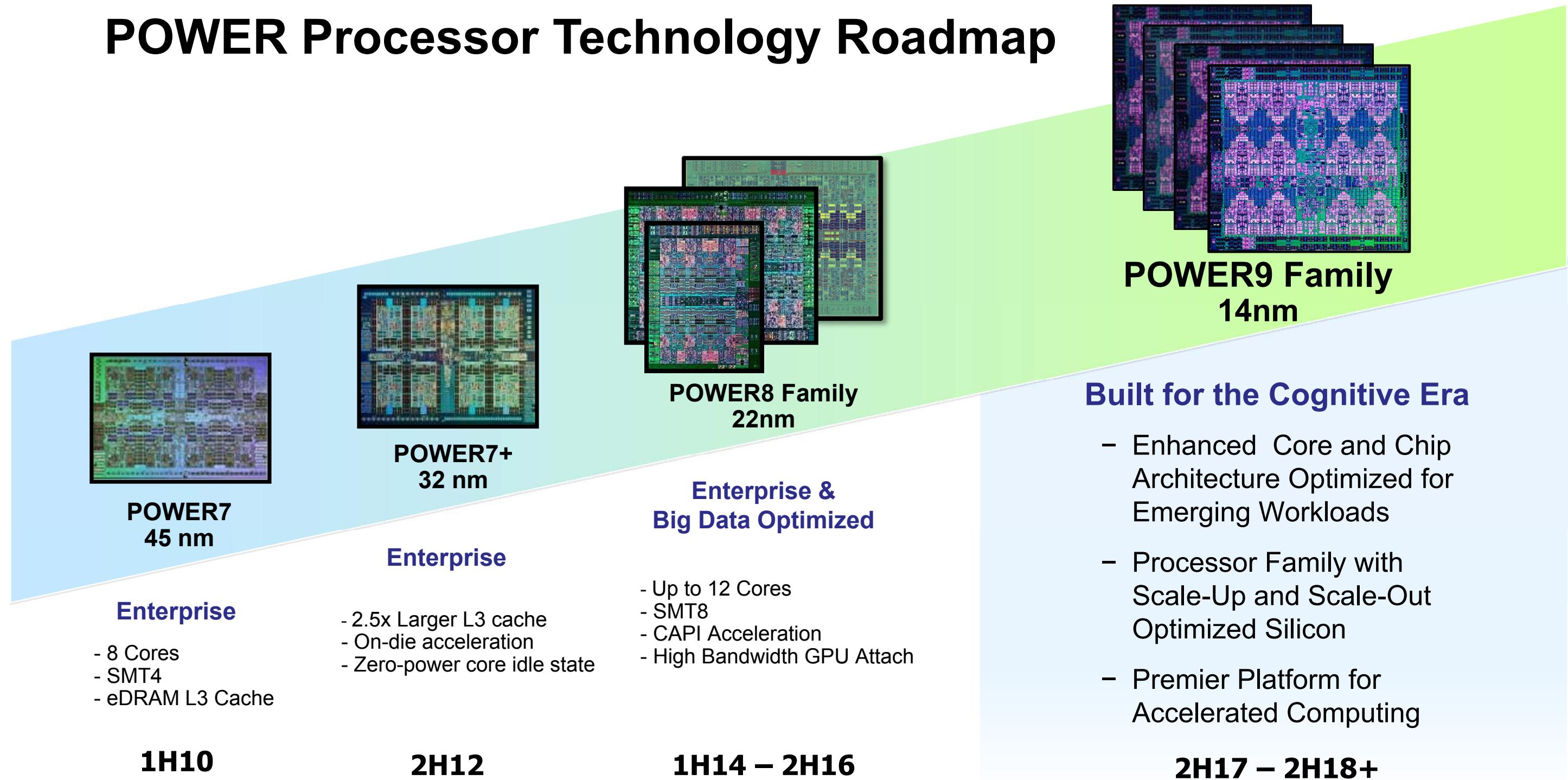
POWER9 Processor for the Cognitive Era

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POWER Systems, IBM Systems



POWER Processor Technology Roadmap



Emerging Analytics, AI, Cognitive

- New core for stronger thread performance
- Delivers 2x compute resource per socket
- Built for acceleration – OpenPOWER solution enablement



DB2 BLU



Caffe

Technical / HPC

- Highest bandwidth GPU attach
- Advanced GPU/CPU interaction and memory sharing
- High bandwidth direct attach memory



Cloud / HSDC

- Power / Packaging / Cost optimizations for a range of platforms
- Superior virtualization features: security, power management, QoS, interrupt
- State of the art IO technology for network and storage performance



Google



Enterprise

- Large, flat, Scale-Up Systems
- Buffered memory for maximum capacity
- Leading RAS
- Improved caching



ORACLE®

New Core Microarchitecture

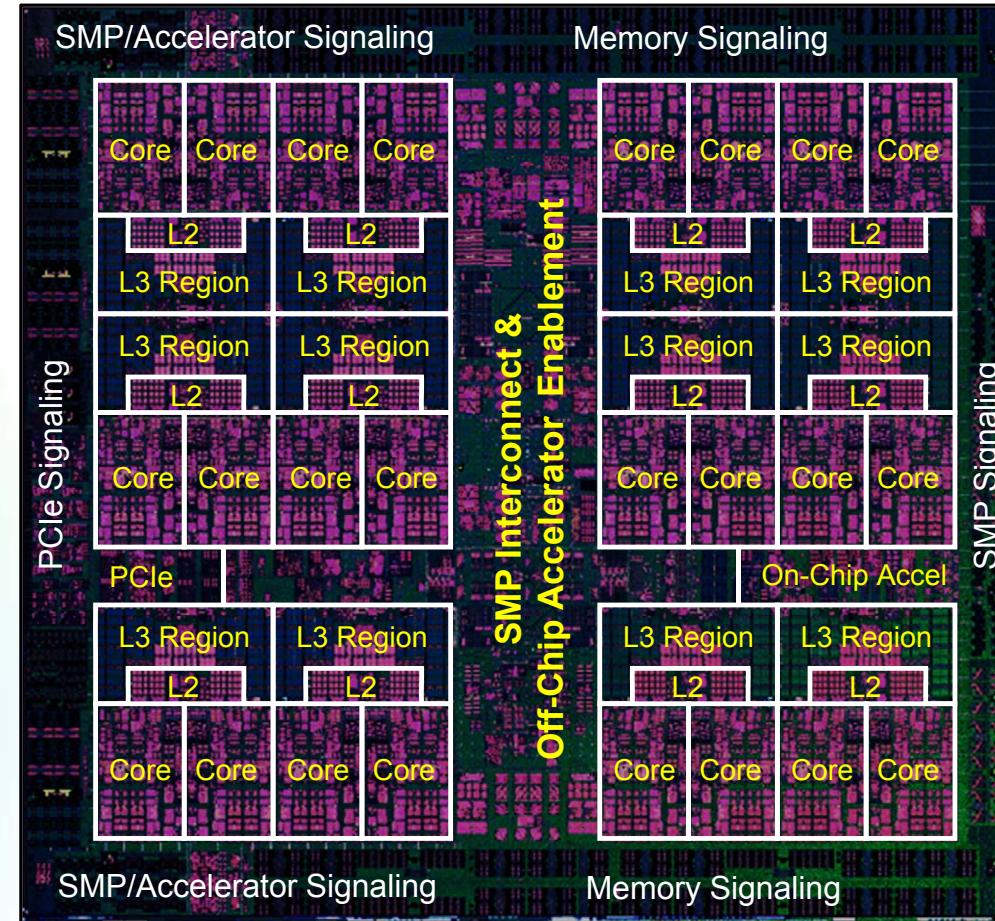
- Stronger thread performance
- Efficient agile pipeline
- POWER ISA v3.0

Enhanced Cache Hierarchy

- 120MB NUCA L3 architecture
- 12 x 20-way associative regions
- Advanced replacement policies
- Fed by 7 TB/s on-chip bandwidth

Cloud + Virtualization Innovation

- Quality of service assists
- New interrupt architecture
- Workload optimized frequency
- Hardware enforced trusted execution



14nm finFET Semiconductor Process

- Improved device performance and reduced energy
- 17 layer metal stack and eDRAM
- 8.0 billion transistors

Leadership Hardware Acceleration Platform

- Enhanced on-chip acceleration
- Nvidia NVLink 2.0: High bandwidth, advanced new features
- CAPI 2.0: Coherent accelerator and storage attach (PCIe G4)
- New CAPI: Improved latency and bandwidth, open interface

State of the Art I/O Subsystem

- PCIe Gen4 – 48 lanes

High Bandwidth Signaling Technology

- 16 Gb/s interface
 - Local SMP
- 25 Gb/s interface – 25G Link
 - Accelerator, remote SMP

Four targeted implementations

SMP scalability / Memory subsystem

Scale-Out – 2 Socket Optimized

Robust 2 socket SMP system

Direct Memory Attach

- Up to 8 DDR4 ports
- Commodity packaging form factor

Core Count / Size

SMT4 Core

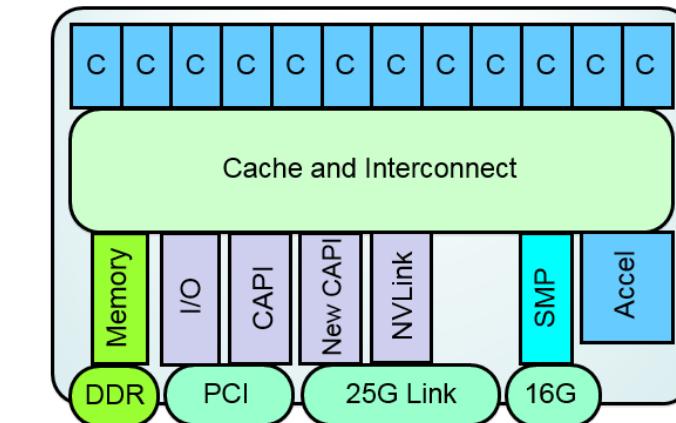
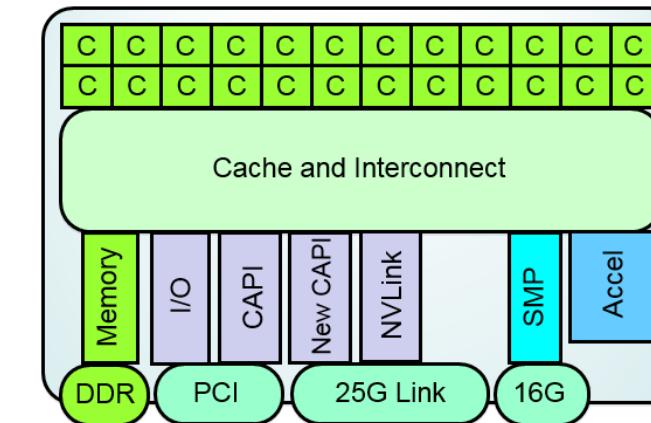
24 SMT4 Cores / Chip

Linux Ecosystem Optimized

SMT8 Core

12 SMT8 Cores / Chip

PowerVM Ecosystem Continuity



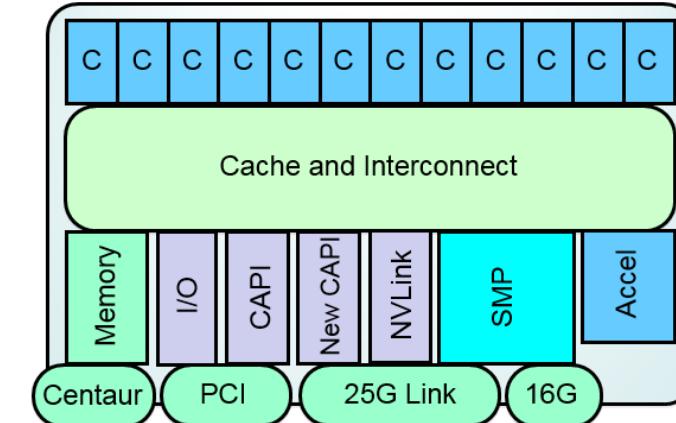
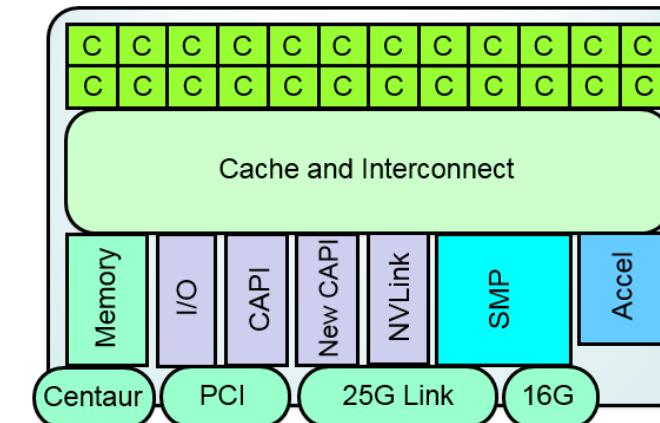
Scale-Up – Multi-Socket Optimized

Scalable System Topology / Capacity

- Large multi-socket

Buffered Memory Attach

- 8 Buffered channels



Optimized for Stronger Thread Performance and Efficiency

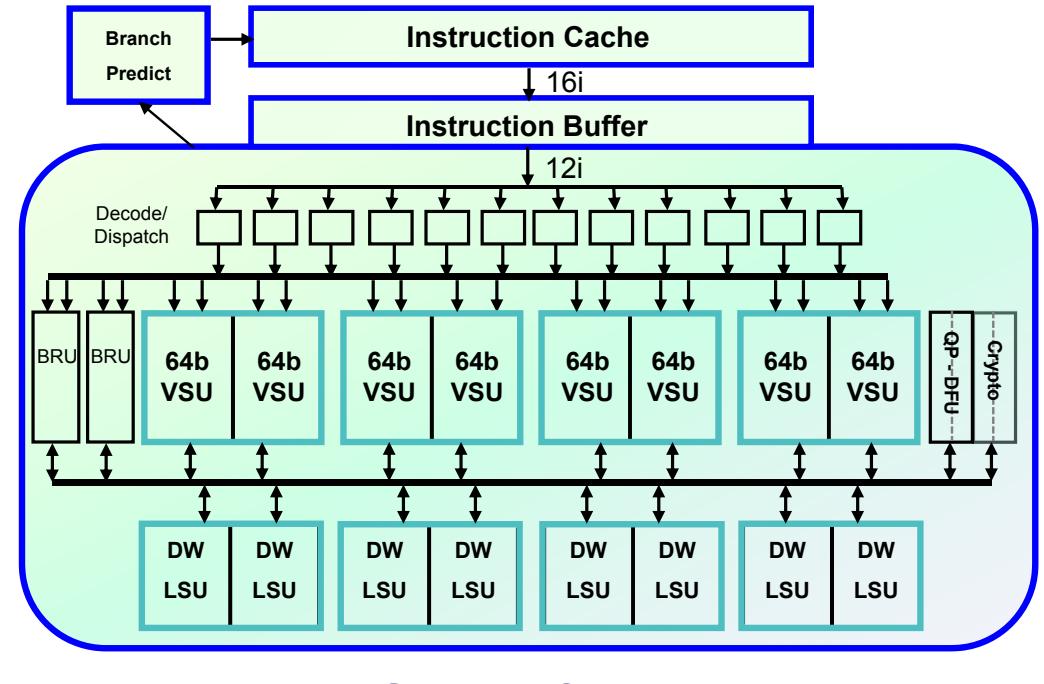
- Increased execution bandwidth efficiency for a range of workloads including commercial, cognitive and analytics
- Sophisticated instruction scheduling and branch prediction for unoptimized applications and interpretive languages
- Adaptive features for improved efficiency and performance especially in lower memory bandwidth systems

Available with SMT8 or SMT4 Cores

8 or 4 threaded core built from modular execution slices

POWER9 SMT8 Core

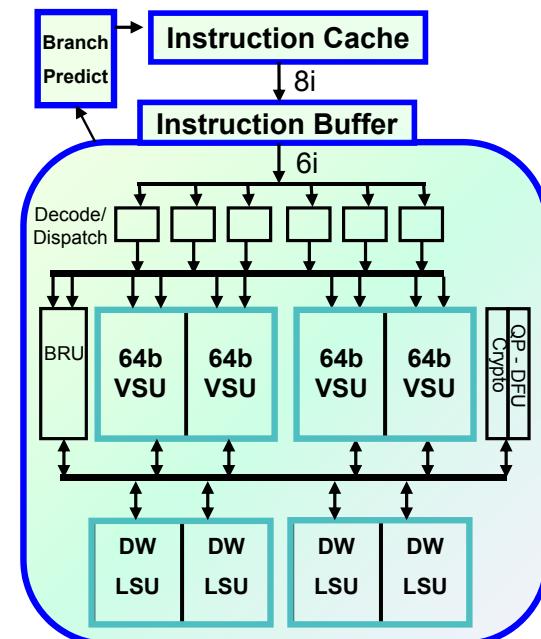
- PowerVM Ecosystem Continuity
- Strongest Thread
- Optimized for Large Partitions



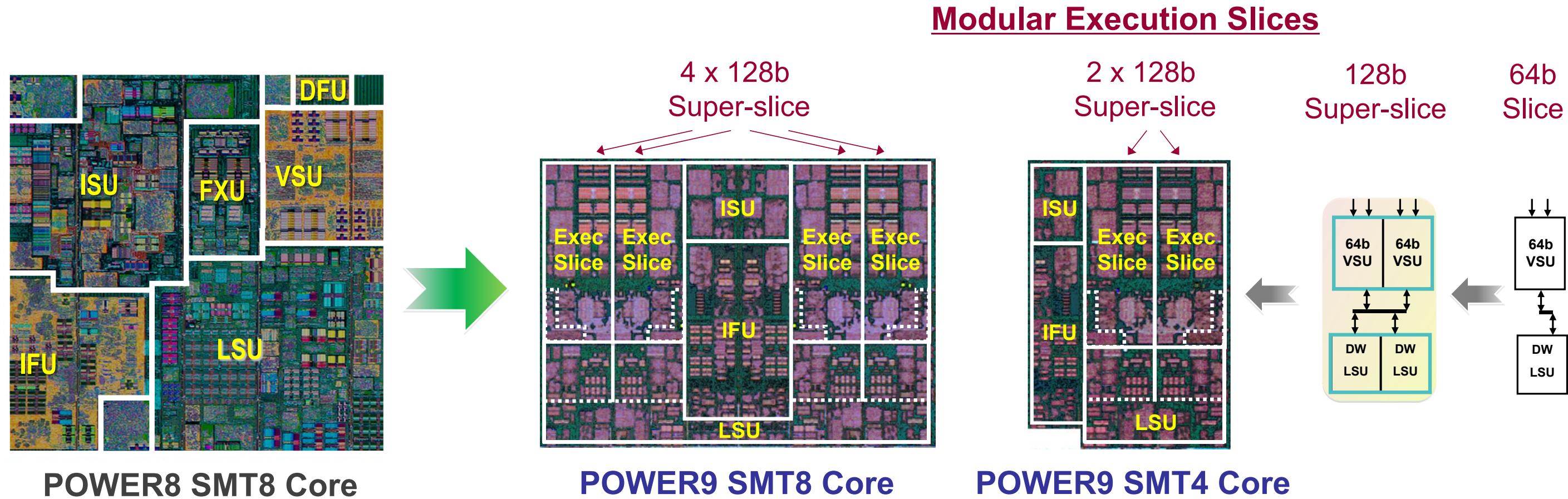
SMT8 Core

POWER9 SMT4 Core

- Linux Ecosystem Focus
- Core Count / Socket
- Virtualization Granularity



SMT4 Core



Re-factored Core Provides Improved Efficiency & Workload Alignment

- Enhanced pipeline efficiency with modular execution and intelligent pipeline control
- Increased pipeline utilization with symmetric data-type engines: Fixed, Float, 128b, SIMD
- Shared compute resource optimizes data-type interchange

Shorter Pipelines with Reduced Disruption

Improved application performance for modern codes

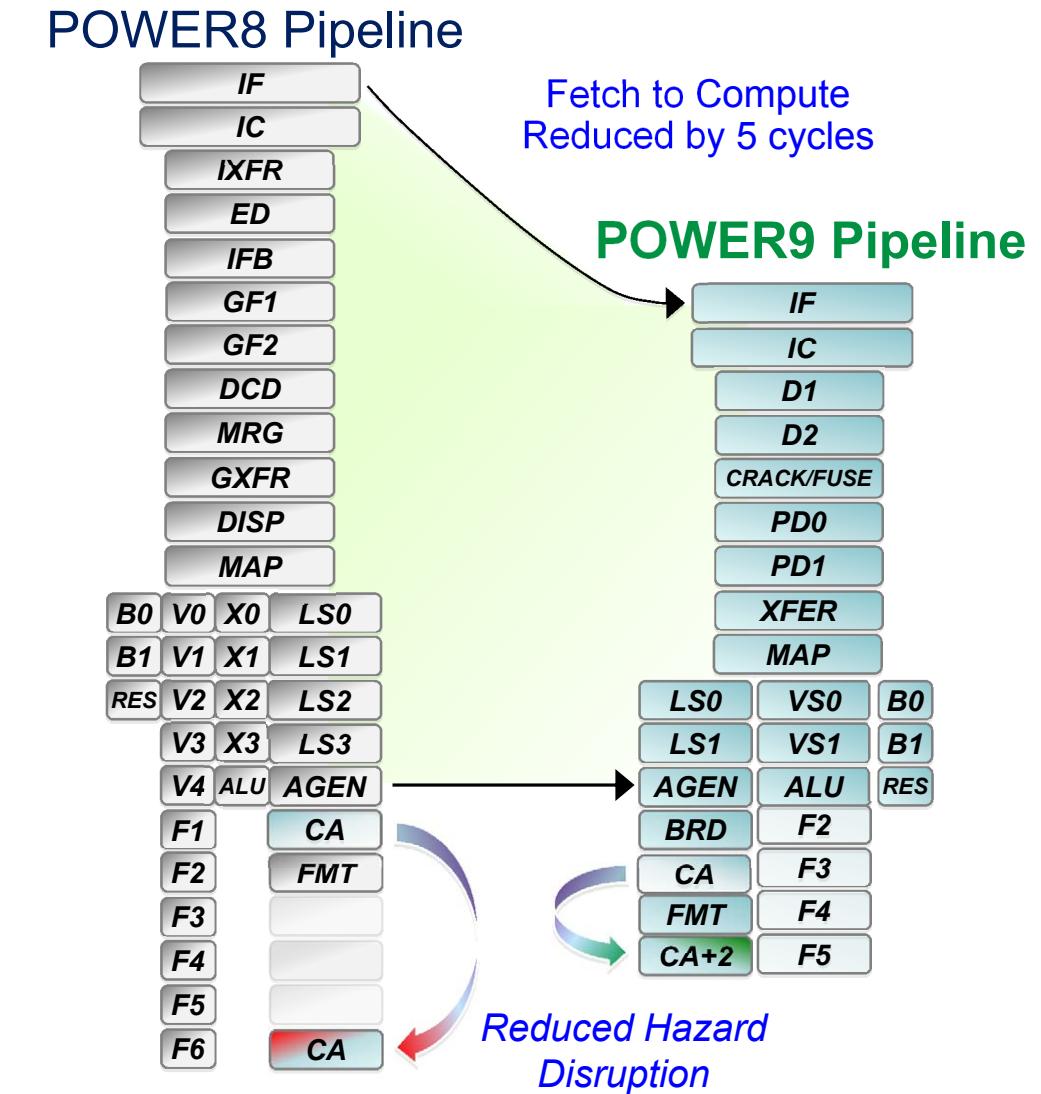
- Shorten fetch to compute by 5 cycles
- Advanced branch prediction

Higher performance and pipeline utilization

- Improved instruction management
 - Removed instruction grouping and reduced cracking
 - Enhanced instruction fusion
 - Complete up to 128 (64 – SMT4 Core) instructions per cycle

Reduced latency and improved scalability

- Local pipe control of load/store operations
 - Improved hazard avoidance
 - Local recycles – reduced hazard disruption
 - Improved lock management



SMT4 Core Resources

Fetch / Branch

- 32kB, 8-way Instruction Cache
- 8 fetch, 6 decode
- 1x branch execution

Slices issue VSU and AGEN

- 4x scalar-64b / 2x vector-128b
- 4x load/store AGEN

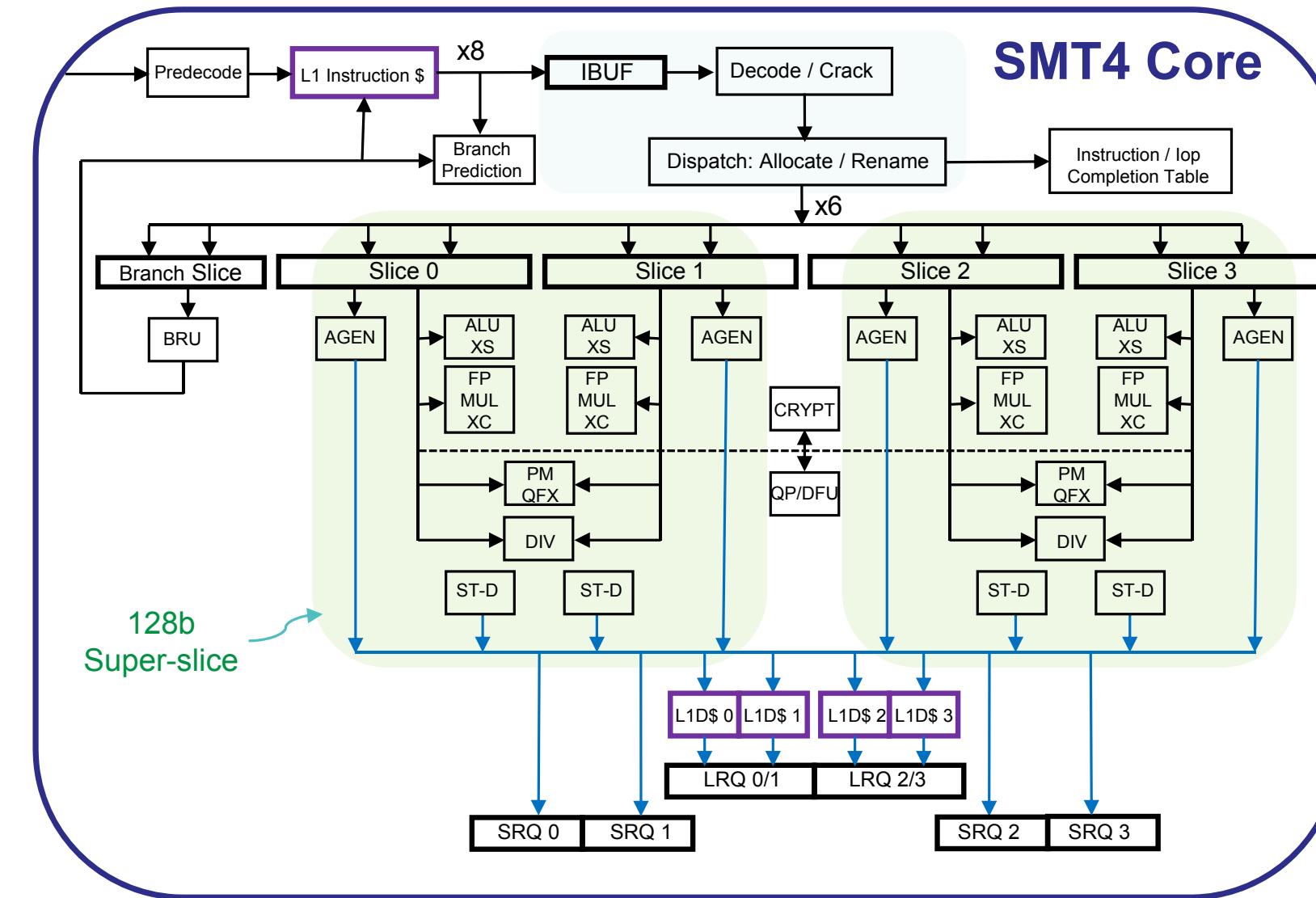
Vector Scalar Unit (VSU) Pipes

- 4x ALU + Simple (64b)
- 4x FP + FX-MUL + Complex (64b)
- 2x Permute (128b)
- 2x Quad Fixed (128b)
- 2x Fixed Divide (64b)
- 1x Quad FP & Decimal FP
- 1x Cryptography

Load Store Unit (LSU) Slices

- 32kB, 8-way Data Cache
- Up to 4 DW load or store

Symmetric Engines Per Data-Type for Higher Performance on Diverse Workloads



Efficient Cores Deliver 2x Compute Resource per Socket

New Instruction Set Architecture Implemented on POWER9

Broader data type support

- 128-bit IEEE 754 Quad-Precision Float – Full width quad-precision for financial and security applications
- Expanded BCD and 128b Decimal Integer – For database and native analytics
- Half-Precision Float Conversion – Optimized for accelerator bandwidth and data exchange

Support Emerging Algorithms

- Enhanced Arithmetic and SIMD
- Random Number Generation Instruction

Accelerate Emerging Workloads

- Memory Atomics – For high scale data-centric applications
- Hardware Assisted Garbage Collection – Optimize response time of interpretive languages

Cloud Optimization

- Enhanced Translation Architecture – Optimized for Linux
- New Interrupt Architecture – Automated partition routing for extreme virtualization
- Enhanced Accelerator Virtualization
- Hardware Enforced Trusted Execution

Energy & Frequency Management

- POWER9 Workload Optimized Frequency – Manage energy between threads and cores with reduced wakeup latency



Big Caches for Massively Parallel Compute and Heterogeneous Interaction

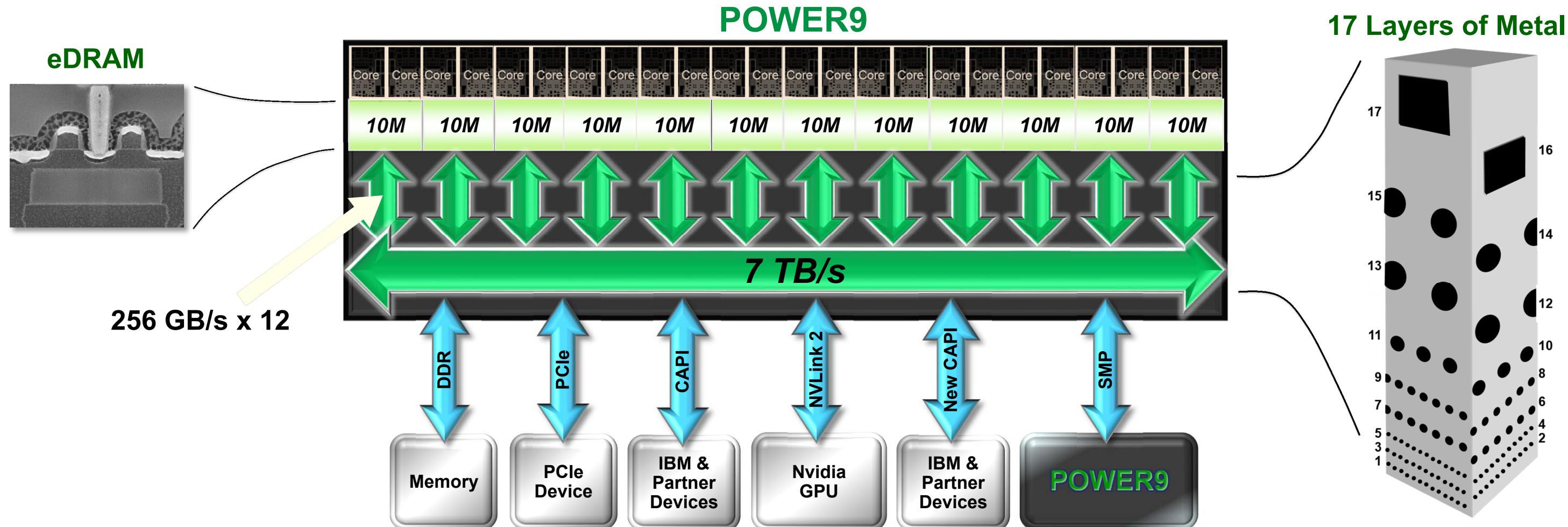
L3 Cache: 120 MB Shared Capacity NUCA Cache

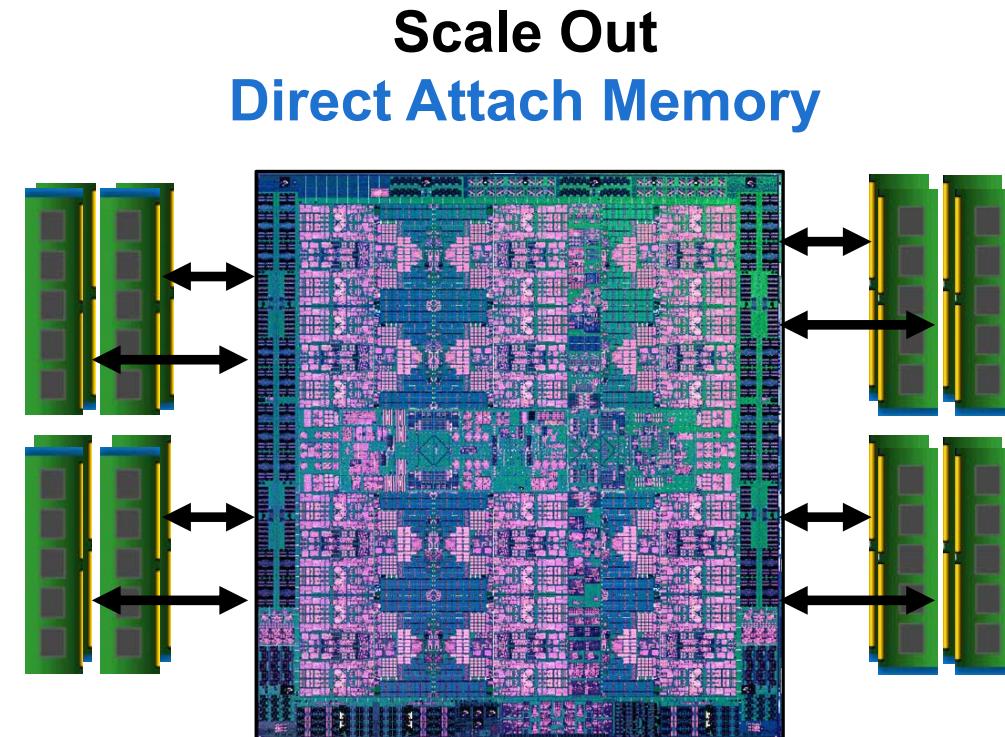
- 10 MB Capacity + 512k L2 per SMT8 Core
- Enhanced Replacement with Reuse & Data-Type Awareness
12 x 20 way associativity

Extreme Switching Bandwidth for the Most Demanding Compute and Accelerated Workloads

High-Throughput On-Chip Fabric

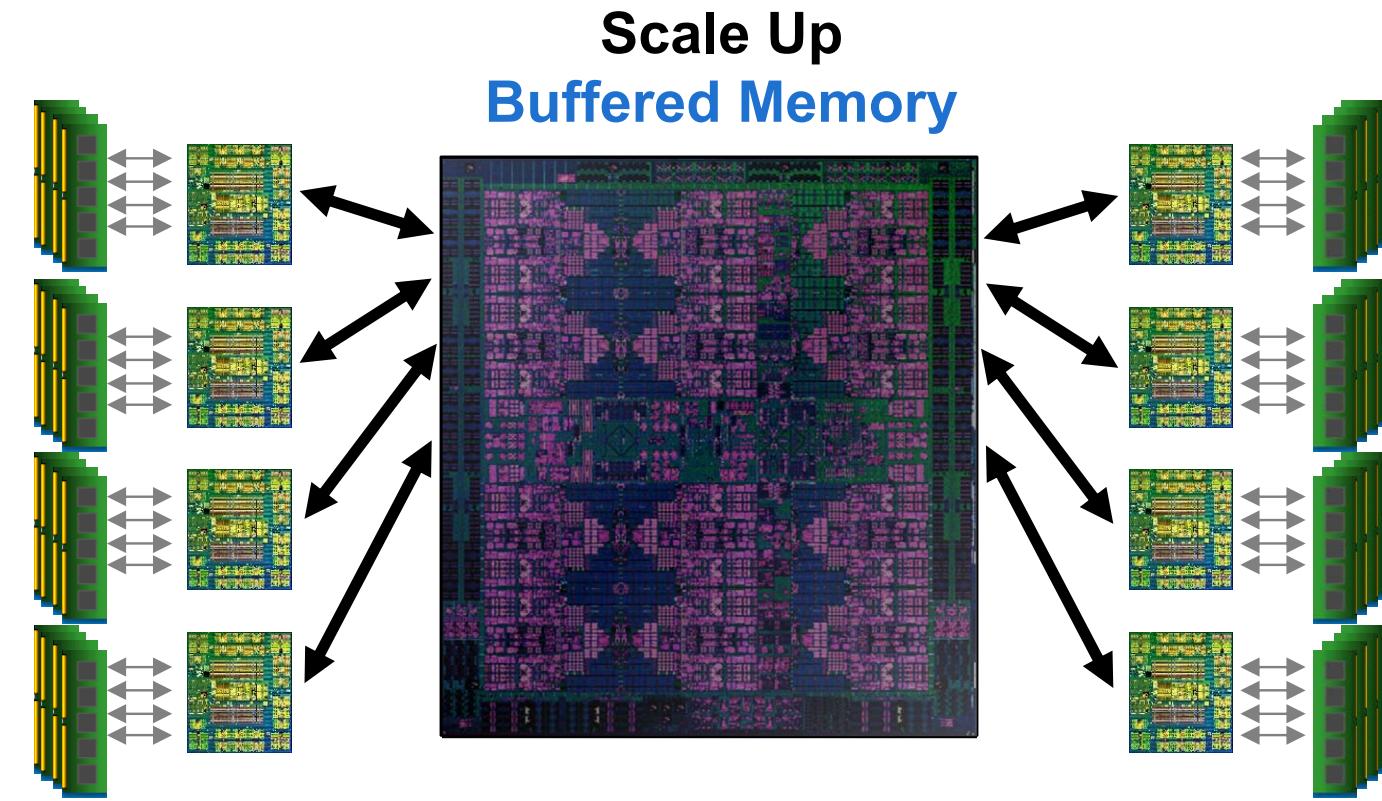
- Over 7 TB/s On-chip Switch
- Move Data in/out at 256 GB/s per SMT8 Core





8 Direct DDR4 Ports

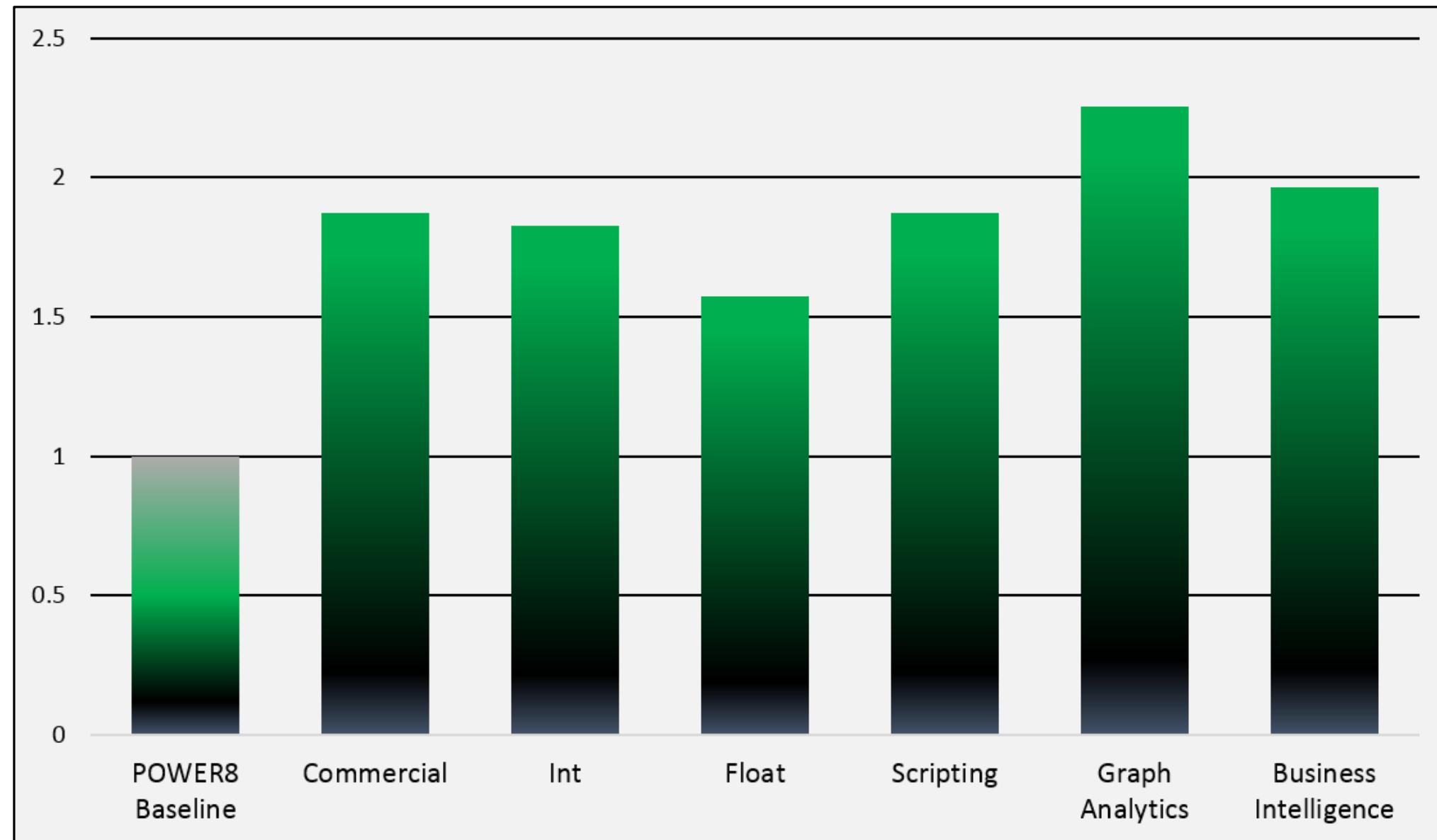
- Up to 120 GB/s of sustained bandwidth
- Low latency access
- Commodity packaging form factor
- Adaptive 64B / 128B reads



8 Buffered Channels

- Up to 230GB/s of sustained bandwidth
- Extreme capacity – up to 8TB / socket
- Superior RAS with chip kill and lane sparing
- Compatible with POWER8 system memory
- Agnostic interface for alternate memory innovations

Socket Performance



Scale-Out configuration @ constant frequency

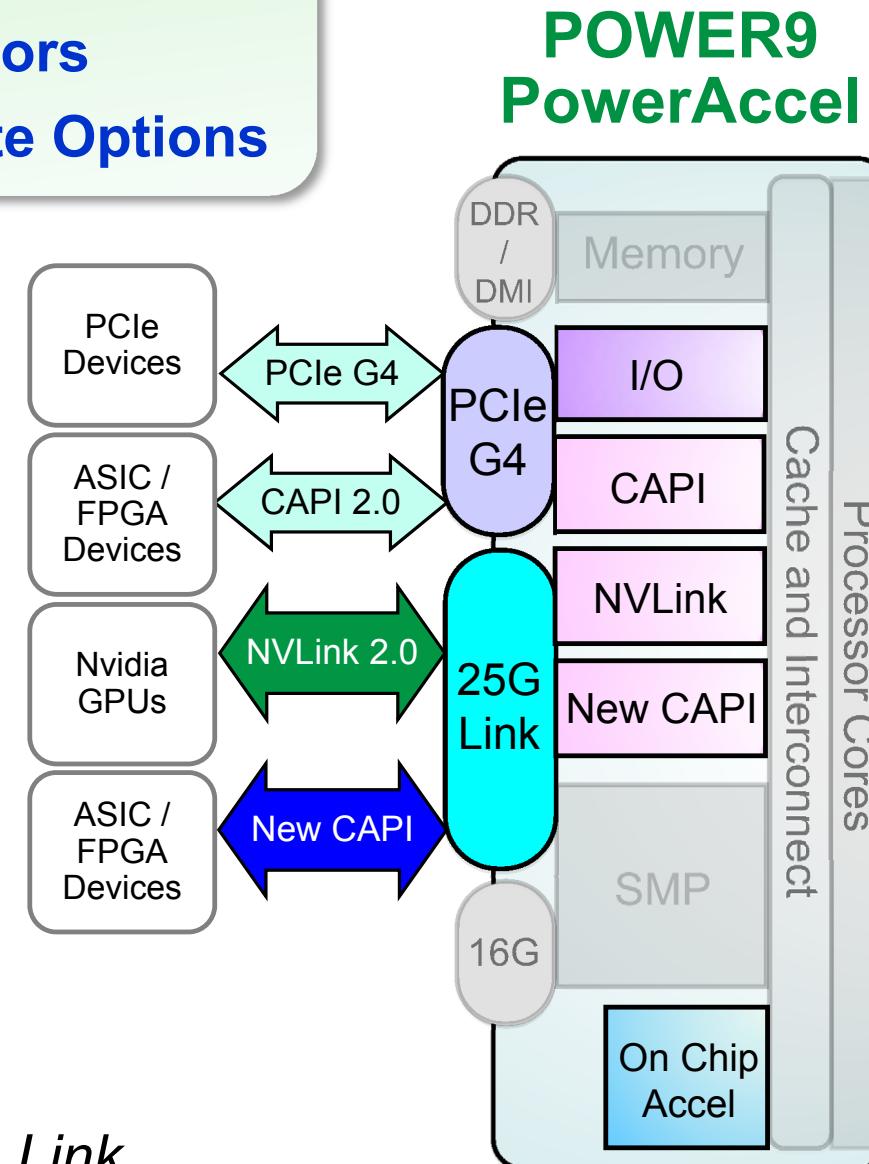
- Extreme Processor / Accelerator Bandwidth and Reduced Latency
- Coherent Memory and Virtual Addressing Capability for all Accelerators
- OpenPOWER Community Enablement – Robust Accelerated Compute Options

- State of the Art I/O and Acceleration Attachment Signaling

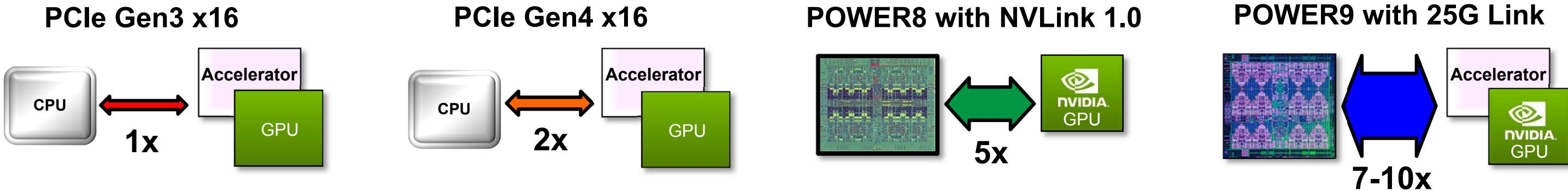
- PCIe Gen 4 x 48 lanes – 192 GB/s duplex bandwidth
 - 25G Link x 48 lanes – 300 GB/s duplex bandwidth

- Robust Accelerated Compute Options with OPEN standards

- On-Chip Acceleration – Gzip x1, 842 Compression x2, AES/SHA x2
 - CAPI 2.0 – 4x bandwidth of POWER8 using PCIe Gen 4
 - NVLink 2.0 – Next generation of GPU/CPU bandwidth and integration
 - New CAPI – High bandwidth, low latency and open interface using 25G Link



Extreme CPU/Accelerator Bandwidth



Seamless CPU/Accelerator Interaction

- Coherent memory sharing
- Enhanced virtual address translation
- Data interaction with reduced SW & HW overhead

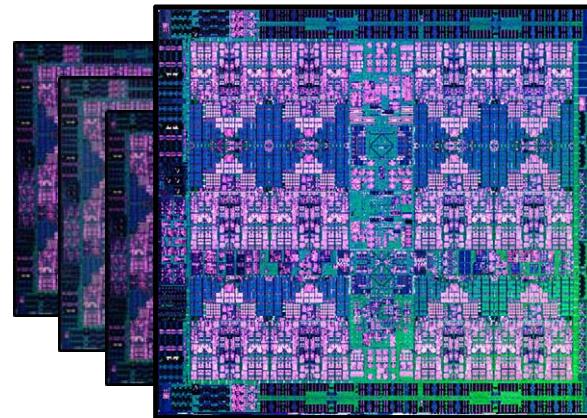
Broader Application of Heterogeneous Compute

- Designed for efficient programming models
- Accelerate complex analytic / cognitive applications

OpenPOWER™ Foundation

- Accelerating Open Innovation
- Grown from 5 to over 200 members in less than 3 years





Built for the Cognitive Era

 **OpenPOWER™**

Enhanced Core and Chip Architecture for Emerging Workloads

- New Core Optimized for Emerging Algorithms to Interpret and Reason
- Bandwidth, Scale, and Capacity, to Ingest and Analyze

Processor Family with Scale-Out and Scale-Up Optimized Silicon

- Enabling a Range of Platform Optimizations – from HSDC Clusters to Enterprise Class Systems
- Extreme Virtualization Capabilities for the Cloud

Premier Acceleration Platform

- Heterogeneous Compute Options to Enable New Application Paradigms
- State of the Art I/O
- Engineered to be Open

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